# MSKSEMI















**ESD** 

**TVS** 

**TSS** 

MOV

**GDT** 

**PLED** 

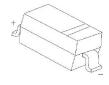
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# Silicon Epitaxial Planar Schottky Barrier Diode

for low current rectification and high speed switching applications



#### **FEATURES**

Low current rectifier s Low voltage, low inductance For power supply



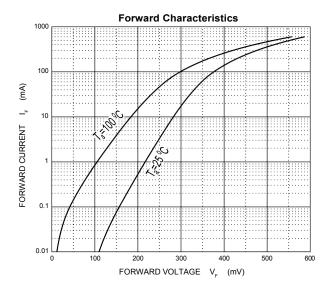
**SOD-323** 

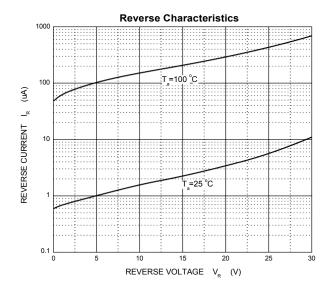
#### Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25℃

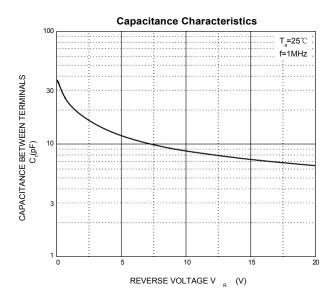
Parameter	Symbol	Limit	Unit
Peak reverse voltage	$V_{RM}$	30	V
DC reverse voltage	V <sub>R</sub>	20	V
Mean rectifying current	lo	0.5	А
Peak forward surge current	I <sub>FSM</sub>	2	А
Power dissipation	Pd	250	mW
Thermal resistance junction to ambient	Reja	400	°C/W
Junction temperature	Tj	125	℃
Storage temperature	$T_{stg}$	-55~+150	℃

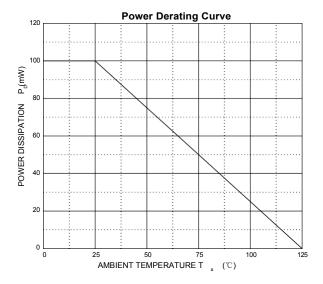
## Electrical Ratings @Ta=25℃

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Forward voltage	V <sub>F</sub>			0.36	V	I <sub>F</sub> =100mA
				0.47		I <sub>F</sub> =500mA
Reverse current	I <sub>R</sub>			100	μA	V <sub>R</sub> =20V

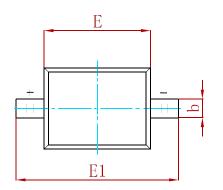


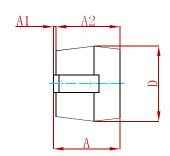


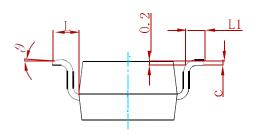




## **PACKAGE MECHANICAL DATA**

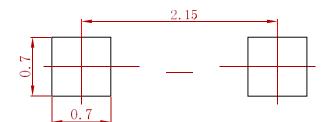






0	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α		1.000		0.039	
A 1	0.000	0.100	0.000	0.004	
A2	0.800	0.900	0.031	0.035	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	1.200	1.400	0.047	0.055	
E	1.600	1.800	0.063	0.071	
E1	2.550	2.750	0.100	0.108	
L	0.47	5 REF.	0.019	REF.	
L1	0.250	0.400	0.010	0.016	
θ	0°	8°	0°	8°	

# **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

### **REEL SPECIFICATION**

P/N	PKG	QTY
RB551V-30-MS	SOD-323	3000



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